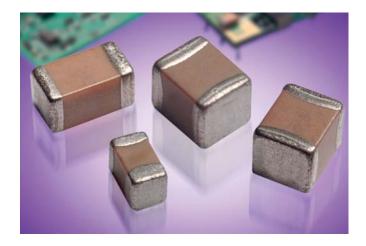
## **Y5V Dielectric**





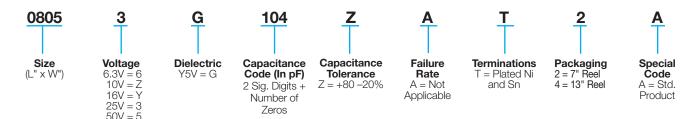


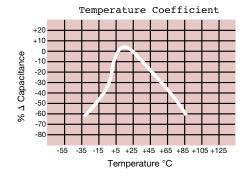
Y5V formulations are for general-purpose use in a limited temperature range. They have a wide temperature characteristic of +22% -82% capacitance change over the operating temperature range of -30°C to +85°C.

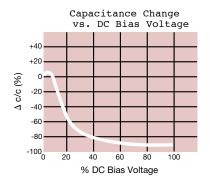
These characteristics make Y5V ideal for decoupling applications within limited temperature range.

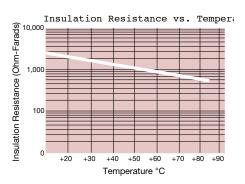


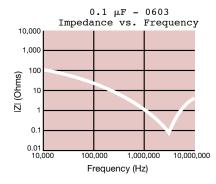
### PART NUMBER (see page 2 for complete part number explanation)

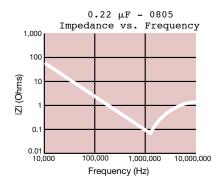


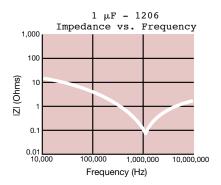














# **Y5V Dielectric**



### **Specifications and Test Methods**

Parame	ter/Test	Y5V Specification Limits	Measuring Conditions							
	perature Range	-30°C to +85°C	Temperature Cycle Chamber							
Capac	itance	Within specified tolerance								
		≤ 5.0% for ≥ 50V DC rating	Freq.: 1.0 kHz ± 10%							
Dissipation	on Factor	≤ 7.0% for 25V DC rating	Voltage: 1.0Vrms ± .2V							
		≤ 9.0% for 16V DC rating	For Cap > 10 μF, 0.5Vrms @ 120Hz							
		≤ 12.5% for ≤ 10V DC rating	01 1 1 1							
Insulation	Resistance	10,000MΩ or 500MΩ - μF,	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity							
		whichever is less								
Dielectric	Strength	No breakdown or visual defects	Charge device with 300% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)							
Resistance to Flexure Stresses	Appearance	No defects	Deflection							
	Capacitance	≤ ±30%	Test Time: 30 seconds							
	Variation			1mm/sec						
	Dissipation Factor	Meets Initial Values (As Above)								
	Insulation Resistance	≥ Initial Value x 0.1	90 mm —							
Solda	rahility	≥ 95% of each terminal should be covered	Dip device in eutectic solder at 230 ± 5°C							
Solderability		with fresh solder	for $5.0 \pm 0.0$	.5 seconds						
Resistance to Solder Heat	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance	≤ ±20%	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.							
	Variation Dissipation									
	Factor	Meets Initial Values (As Above)								
	Insulation									
	Resistance	Meets Initial Values (As Above)								
	Dielectric									
	Strength	Meets Initial Values (As Above)								
Thermal Shock	Appearance	No visual defects	Step 1: -30°C ± 2°	30 ± 3 minutes						
	Capacitance	≤ ±20%	Step 2: Room Temp	≤ 3 minutes						
	Variation									
	Dissipation	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes						
	Factor									
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes						
	Dielectric		Repeat for 5 cycles and measure after							
	Strength	Meets Initial Values (As Above)	24 ±2 hours at room to							
	Appearance	No visual defects								
	Capacitance	≤ ±30%	Charge device with twice rated voltage in							
	Variation	3 10070	test chamber se							
	Dissipation	≤ Initial Value x 1.5 (See Above)	for 1000 hou	urs (+48, -0)						
Load Life	Factor	2 milar value // 110 (000 / 100 vo)	Dama ay a fuana ta at ab	a a mala a u a mala ata la ilima						
	Insulation	≥ Initial Value x 0.1 (See Above)	Remove from test ch							
	Resistance Dielectric	,	at room temperature for 24 ± 2 hours before measuring.							
	Strength	Meets Initial Values (As Above)	DOIOIG III	oacai ii ig.						
Load Humidity	Appearance	No visual defects	0							
	Capacitance	≤ ±30%	Store in a test chamb							
	Variation	≥ ±3U70	85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied.  Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.							
	Dissipation	≤ Initial Value x 1.5 (See above)								
	Factor	≥ II III.ai value x 1.3 (See abuve)								
	Insulation	≥ Initial Value x 0.1 (See Above)								
	Resistance									
	Dielectric Strength	Meets Initial Values (As Above)		<u> </u>						
	Suengui	` ′								



# **Y5V Dielectric**





#### PREFERRED SIZES ARE SHADED

							<b>600</b>					ш	1												
SIZE	SIZE 0201		0402				0603				0805				1206				1210						
Soldering Reflow Only		Reflow/Wave			Reflow/Wave				Reflow/Wave				Reflow/Wave				Reflow Only								
Packaging All Paper		All Paper				All Paper				Paper/Embossed				Paper/Embossed				Paper/Embossed							
(L) Length	mm (in.)		± 0.03 ± 0.001)			1.00 ± 0.10 (0.040 ± 0.004)			1.60 ± 0.15 (0.063 ± 0.006)				2.01 ± 0.20 (0.079 ± 0.008)				3.20 ± 0.20 (0.126 ± 0.008)				3.20 ± 0.20 (0.126 ± 0.008)				
(W) Width	mm (in.)		± 0.03 ± 0.001)	0.50 ± 0.10 (0.020 ± 0.00					.81 ± 0.15 (0.032 ± 0.006)				1.25 ± 0.20 (0.049 ± 0.008)				1.60 ± 0.20 (0.063 ± 0.008)				2.50 ± 0.20 (0.098 ± 0.008)				
(t) Terminal	mm (in.)		± 0.05 ± 0.002)			0.25 ± 0.15 (0.010 ± 0.006)			0.35 ± 0.15 (0.014 ± 0.006)			0.50 ± 0.25 (0.020 ± 0.010)				0.50 ± 0.25 (0.020 ± 0.010)				.50 ± 0.25 (0.020 ± 0.010)					
	WVDC	6.3	10	6	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	
Cap (pF)	820 1000 2200		A A																					<u> </u>	
Cap (µF)	4700 0.010 0.022	A A	A A																				$\mathcal{D}$	T	
	0.047 0.10 0.22	А			С	C				G	G	G				K				I					
	0.33 0.47					С				G G	G														
	1.0			С	С	_			G	G	J			N	N	N		М	М	М				N	
	2.2				С				J					N	N				K	Q					
	4.7												N	N	N			Р	Q			N	N	İ	
	10.0												N	Р			Q	Q	Х		Х	Q	Q		
	22.0 47.0																Q				Χ	Z		Ì	
	WVDC	6.3	10	6	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	
SIZE		0201			0402			0603			0805				1206				1210						
Letter	Letter A C E G J K M N P Q X Y Z																								
Max.	0.33		56	0.71		0.90	0.9	4	1.02	1	.27	1.40	)	1.52		78	2.29	9	2.54		<del>-</del> 79				
Thickness	(0.013)		022)	(0.028		).035)	(0.03		(0.040		.050)	(0.05		(0.060)	(0.0	070)	(0.09		(0.100)		110)				

